PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
SHUNPEI YAMAZAKI	07/11/2018
HAJIME KIMURA	07/09/2018
TAKANORI MATSUZAKI	07/10/2018
KIYOSHI KATO	07/12/2018
SATORU OKAMOTO	07/31/2018

RECEIVING PARTY DATA

Name:	Semiconductor Energy Laboratory Co., Ltd.	
Street Address:	398, Hase	
City:	Atsugi-shi, Kanagawa-ken	
State/Country:	JAPAN	
Postal Code:	243-0036	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16004890

CORRESPONDENCE DATA

Fax Number: (703)766-2394

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (571) 434-6789
Email: uspto@riplo.com
Correspondent Name: ERIC J. ROBINSON

Address Line 1: ROBINSON IP LAW OFFICE, P.C.

Address Line 2: 3975 FAIR RIDGE DRIVE, SUITE 20 NORTH

Address Line 4: FAIRFAX, VIRGINIA 22033

NAME OF SUBMITTER: ERIC J. ROBINSON SIGNATURE: /Eric J. Robinson/ DATE SIGNED: 08/03/2018	TTORNEY DOCKET NUMBER: 0756-11623	
	NAME OF SUBMITTER:	ERIC J. ROBINSON
DATE SIGNED: 08/03/2018	SIGNATURE:	/Eric J. Robinson/
DATE GIGHTED.	DATE SIGNED:	08/03/2018

Total Attachments: 4

PATENT REEL: 046546 FRAME: 0584

505034623



ASSIGNMENT

Serial No. <u>16/004,890</u>

Filed June 11, 2018

WHEREAS, Shunpei YAMAZAKI, Hajime KIMURA, Takanori MATSUZAKI, Kiyoshi KATO and Satoru OKAMOTO

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in <u>SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE</u> for which an application for Letters Patent of the United States of America has been executed by the undersigned on , and;

WHEREAS, <u>Semiconductor Energy Laboratory Co., Ltd.</u> of <u>398</u>, <u>Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan</u> and its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from

said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby convenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of ROBINSON INTELLECTUAL PROPERTY LAW OFFICE the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

In witness thereof, this Assignment has been executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 0 9/11/20/8	Signature Shunpei YAMAZAKI
Date	SignatureName Hajime KIMURA
Date	SignatureName Takanori MATSUZAKI
Date	SignatureName Kiyoshi KATO
Date	SignatureName Satoru OKAMOTO
Notary Public. If not, ther	ald preferably be acknowledged before a United States Consul or in the execution by the Inventor(s) should be witnessed has (have) useful improvements in by at least two other persons who should
Witness	Signature
Witness	Signature
Witness	Signature

ASSIGNMENT

Serial No. 16/004,890

Filed June 11, 2018

WHEREAS, Shunpei YAMAZAKI, Hajime KIMURA, Takanori MATSUZAKI, Kiyoshi KATO and Satoru OKAMOTO

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in <u>SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE</u> for which an application for Letters Patent of the United States of America has been executed by the undersigned on , and;

WHEREAS, <u>Semiconductor Energy Laboratory Co.</u>, <u>Ltd.</u> of <u>398</u>, <u>Hase</u>, <u>Atsugi-shi</u>, <u>Kanagawa-ken</u>, <u>243-0036 Japan</u> and its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

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In witness thereof, this Assignment has been executed by the undersigned on the date(s) opposite the undersigned name(s).

Date	Signature	
		Shunpei YAMAZAKI
Date <u>07 / 69 / 201</u> 8	Signature Name	Hajime KIMURA
Date_ 57/10/2018_	Signature Name	Takanori MATSUZAKI
Date 07/12/2018	Signature Name	Kiyoshi KATO
Date 07/31/2018	Signature Name	Satoru OKAMOTO
Notary Public. If not, then	the execu	bly be acknowledged before a United States Consul on tion by the Inventor(s) should be witnessed has (have provements in by at least two other persons who should
Witness		Signature
Witness		Signature
Witness	,	Signature